

Title (en)
CIRCUIT BOARD WITH A HEAT-CONDUCTING ELEMENT

Title (de)
SCHALTUNGSTRÄGER MIT EINEM WÄRMELEITELEMENT

Title (fr)
SUPPORT DE CIRCUIT MUNI D'UN ÉLÉMENT CONDUCTEUR DE CHALEUR

Publication
EP 3180967 A1 20170621 (DE)

Application
EP 15734593 A 20150623

Priority

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- EP 2015064027 W 20150623

Abstract (en)
[origin: WO2016023663A1] The invention relates to a circuit board having at least one electrically insulating layer and at least one electrically conductive layer. The circuit board has at least one heat-conducting element which is embedded in the electrically insulating layer and which is of thermally conductive form. The heat-conducting element is designed to transport heat losses transversely with respect to an areal extent of the circuit board. According to the invention, the heat-conducting element has at least two sub-elements formed in each case by a metal body. The heat-conducting element has an electrically insulating connecting layer which is arranged between the sub-elements and which is designed to electrically insulate the sub-elements with respect to one another and connect the sub-elements to one another in thermally conductive fashion.

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Citation (search report)
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